PRODUCT ADVANTAGE

- High Reliability
- Increase Throughput
- 5X Reflow Cycles
- Simplify Assembly Process
- Low and High Temperature Curing Options
- Filled & Unfilled Options
- Good For Miniaturization

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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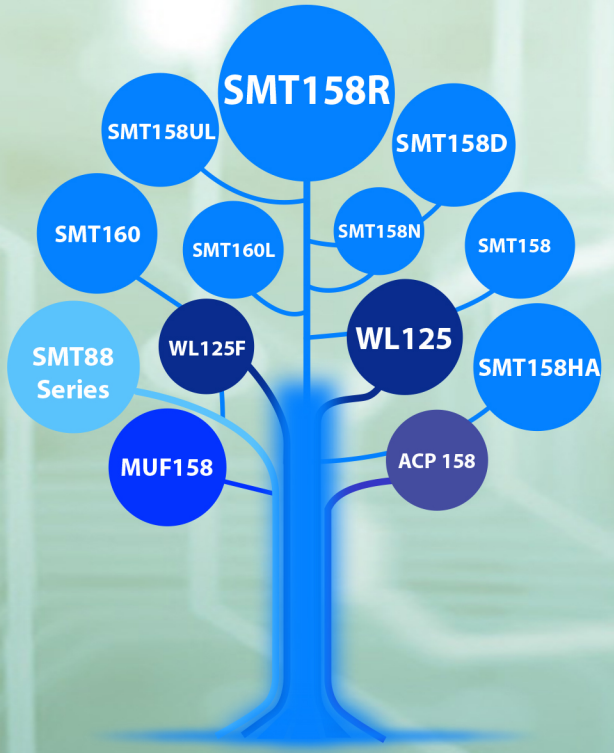
YINCAE®

INNOVATION AT ITS BEST



Underfill Materials

Filled Reflowable Underfill SMT 158R

Preferred by global leaders in the electronics manufacturing industry

YINCAE® SMT 158R Underfill

YINCAE® has recently developed a filled reflowable (no - flow) underfill: SMT 158R. This material is designed to eliminate capillary underfill, simplify the assembly process, combine soldering and underfilling in SMT processes, and increase throughput.

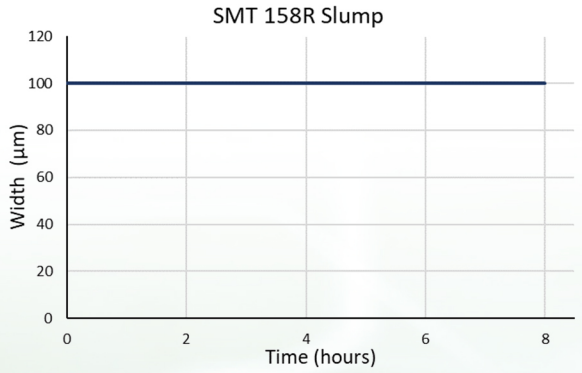
Reflowable underfills are dispensed or printed onto the board before component placement occurs. The design of the material allow it to remain in place so that component placement can occur in a subsequent step.

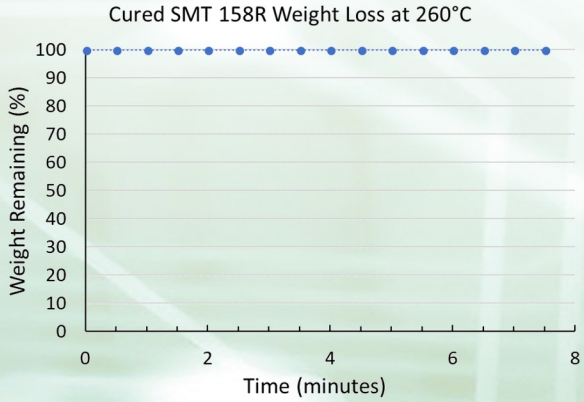
This material is especially helpful for applications with a narrow footprint.

Filled Reflowable Underfill SMT 158R

TYPICAL PHYSICAL PROPERTIES

Product Name	SMT 158R Filled Fluxing Underfill
PROPERTIES OF UNCURED MATERIAL	
Appearance	White
Specific Gravity (ASTM D 1475-60)	1.5 g/cc
Viscosity (Brookfield. 0.5 rpm)	70 – 120 kcp
PROPERTIES OF CURED MATERIAL	
Glass Transition Temperature (Tg) Via TMA (ASTM D3418-82)	125°C
C.T. E (ASTM E 831). PPM /°C	α1 = 50: α2 = 135
Lap Shear Strength (FR4/FR4)	2600 psi
Extractable ions (MIL-STD-883E)	
Na+	<5ppm
K+	<5ppm
F-	<5ppm
Cl-	<10ppm
Surface insulation resistance (J-STD-004)	Pass





SMT 158R is a void free underfill and exhibits no slump when printed

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.